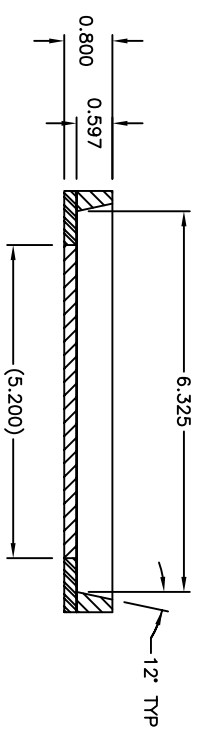
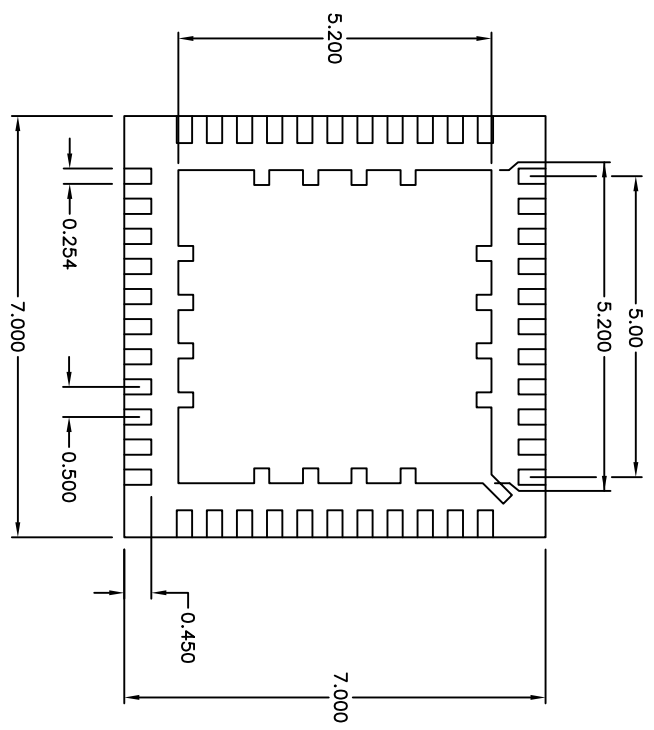
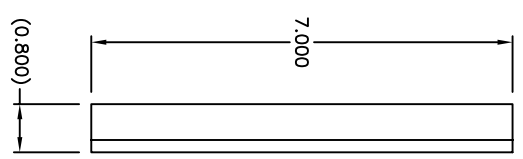
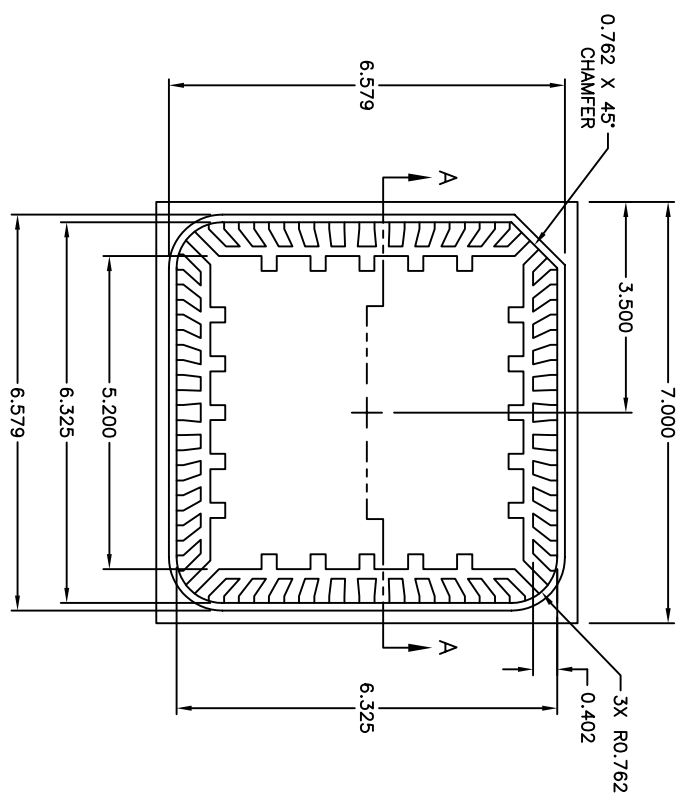


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REVISIONS			APPROVED
ECN NO.	DATE	DESCRIPTION	
10499	10/27/05	PRODUCTION RELEASE	D.BENANDIO



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, FH 194.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ± 0.0076.
 5. DIE PAD: 5.200mm X 5.200mm.
 6. DIE PAD: 5.200mm X 5.200mm.
 7. JEDEC OUTLINE: MO-220 (VKKD-1).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± 0.0050 ANGLES: ± 1'

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	10/26/05
CHKD BY	P. FLASKERUD	DATE	10/26/05
CUSTOMER	---		

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44 Lead 7mm x 7mm
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP7X7-44-OP-01	3

SCALE NONE

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